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1. DMEA13B-001: Electrochemical Micro-Capacitors Utilizing Carbon Nanostructures

   Release Date: 07-26-2013Open Date: 08-26-2013Due Date: 09-25-2013Close Date: 09-25-2013

   TECHNOLOGY AREAS: Materials/Processes, Electronics The technology within this topic is restricted under the International Traffic in Arms Regulation (ITAR), which controls the export and import of defense-related material and services. Offerors must disclose any proposed use of foreign nationals, their country of origin, and what tasks each would accomplish in the statement of work in accordan ...

   STTR Department of DefenseDefense Microelectronics Activity

2. DMEA132-001: Miniaturized RF over Fiber

   Release Date: 04-24-2013Open Date: 05-24-2013Due Date: 06-26-2013Close Date: 06-26-2013

   OBJECTIVE: Design and prototype a capability to use fiber optic cable to simultaneously distribute power (i.e power over fiber) while providing full duplex information flow. The capability will allow miniature microwave system components to be distributed over a relatively long distance (i.e. 30 meters or more) via fiber optics. For example, a processing node (within a microwave system) provid ...

   SBIR Defense Microelectronics Activity

3. DMEA132-002: High Resolution Three-Dimensional Digital Reconstruction of Integrated Circuits

   Release Date: 04-24-2013Open Date: 05-24-2013Due Date: 06-26-2013Close Date: 06-26-2013

   OBJECTIVE: Develop a system for the accurate identification and analysis of semiconductor materials with integrated, high-resolution imaging capability for the three-dimensional digital reconstruction of integrated circuits (ICs). DESCRIPTION: As semiconductor geometries continue to diminish, so too does the applicability of traditional sample preparation tools. As the thickness of metal l ...

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